

Title (en)

CHIP CARD AND METHOD FOR PRODUCTION OF A CHIP CARD

Title (de)

CHIPKARTE UND VERFAHREN ZUR HERSTELLUNG EINER CHIPKARTE

Title (fr)

CARTE A PUCE ET SON PROCEDE DE REALISATION

Publication

**EP 1958131 A2 20080820 (DE)**

Application

**EP 06828581 A 20061130**

Priority

- DE 2006002126 W 20061130
- DE 102005058101 A 20051205

Abstract (en)

[origin: CA2631744A1] The invention relates to a chip card and a method for production of a chip card (41), comprising a chip module which makes contact with an external contact arrangement (31) arranged on the contact surface (51) of a card body and an antenna device arranged in a card inlay, wherein firstly the card inlay is produced in a first production device and subsequently both sides of the card inlay are provided with at least one outer layer (45, 46; 47, 48) in a second production device, such that the outer contact arrangement (31) arranged on the outer contact side of the chip support is introduced into a recess of the provided outer layer and subsequently a connection of the card inlay to the outer layer is carried out in a lamination process.

IPC 8 full level

**G06K 19/077** (2006.01)

CPC (source: EP KR US)

**G06K 19/07** (2013.01 - KR); **G06K 19/077** (2013.01 - KR); **G06K 19/07749** (2013.01 - EP US); **G06K 19/0775** (2013.01 - EP US); **G06K 19/07769** (2013.01 - EP US); **Y10T 29/49018** (2015.01 - EP US)

Citation (search report)

See references of WO 2007065404A2

Citation (examination)

- US 6179210 B1 20010130 - HAAS KEVIN L [US], et al
- WO 2004006173 A2 20040115 - GIESECKE & DEVRIENT GMBH [DE], et al
- DE 102006003835 A1 20070222 - FRAUNHOFER GES FORSCHUNG [DE]

Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IS IT LI LT LU LV MC NL PL PT RO SE SI SK TR

DOCDB simple family (publication)

**DE 102005058101 A1 20070606**; **DE 102005058101 B4 20190425**; BR PI0619427 A2 20111004; CA 2631744 A1 20070614; CA 2631744 C 20120124; CN 101341499 A 20090107; CN 101341499 B 20130130; EP 1958131 A2 20080820; JP 2009518720 A 20090507; KR 101035047 B1 20110519; KR 20080098360 A 20081107; MY 154934 A 20150828; US 2008314990 A1 20081225; WO 2007065404 A2 20070614; WO 2007065404 A3 20070802

DOCDB simple family (application)

**DE 102005058101 A 20051205**; BR PI0619427 A 20061130; CA 2631744 A 20061130; CN 200680045216 A 20061130; DE 2006002126 W 20061130; EP 06828581 A 20061130; JP 2008543646 A 20061130; KR 20087016388 A 20061130; MY PI20081902 A 20061130; US 9600606 A 20061130